chanhvinh.com

BASIC BLADE & BEAM HEADER & SOCKET



(0.80 mm) .0315" PITCH • BTE/BSE SERIES

BTE
Mates:
BSE

BSE
Mates:
BTE

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
2 A per pin
(2 pins powered)
Voltage Rating:
225 VAC/318 VDC
Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (020-080)
(0.15 mm) .006" max (100-120)*
*(.004" stencil solution may be available; contact ipg@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

ALSO AVAILABLE
Contact Samtec

30 µ" (0.76 µm) Gold
Edge Mount Capability
Friction Lock option
11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.)

10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

Note:
Some lengths, styles and options are non-standard, non-returnable.

BTE – NO. OF POSITIONS PER ROW – LEAD STYLE – PLATING OPTION – D – A – OTHER OPTION

–020, –040,–060, –080, –100, –120

Specify LEAD STYLE from chart

–F
= Gold Flash on contact, Matte Tin on tail

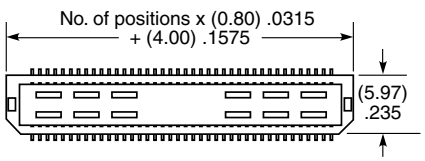
–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails (*–C Plating passes 10 year MFG testing)

–K
= (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

–TR
= Tape & Reel (80 positions maximum)

–FR
= Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (80 positions maximum)



LEAD STYLE	A
–01	(4.27) .168
–02	(7.21) .284

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(5.00 mm) .197"
–02	(8.00 mm) .315"

*Processing conditions will affect mated height.

BSE – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

–020, –040, –060, –080, –100, –120

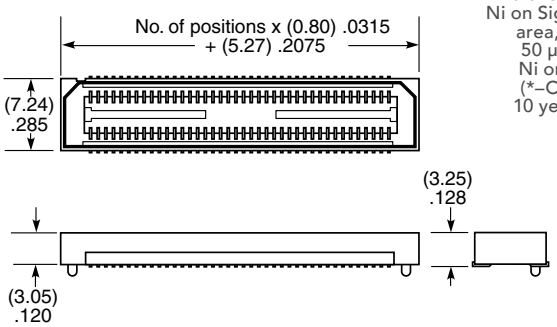
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Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.